



Le880SLVVP VeriVoice Professional Software P1.8.0

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This document describes new features and corrected errata for the Le880SLVVP VeriVoice™ Professional Software. Refer to the Line Test API User's Guide (Document ID #081470), Rev 22 for more details.

1.0 REVISION SUMMARY

This is a bug fix and feature addition to revision P1.7.2 of the Le880SLVVP software. *This release replaces all previous release.*

This release provides a complete set of the available VeriVoice Professional tests as described in Table 2-2 of the LT-API User's Guide.

PLEASE READ THE FOLLOWING CAREFULLY

This release is compatible with the following VP-API-II release packages:

- LE71SK0002 P2.17.0 to P2.23.0
- LE71SDKAPIL P2.17.0 to P2.23.0

2.0 SOURCE FILES

The release package has the following file/folder structure:

- `\ReadMe.txt` - High level installation instructions.
- `\api_lib\vp880_api` - VE880 VP-API-II extension source files (primitives).
- `\lt_api\common` - LT-API interface implementation files.
- `\lt_api\documents` - LT-API User's Guide and this document.
- `\lt_api\includes` - LT-API interface definition source files.
- `\lt_api\vp880_lt` - LT-API interface definition source files.

Details pertaining to the source files can be found in the LT-API User's Guide section 1.3.

All source files were updated to replace the Zarlink Copyright notice with the Microsemi Copyright notice.

3.0 CORRECTED ERRATA FROM P1.7.2

- C1** Prevent VP-API ring cadencer from interfering with the Ringing Self Test (LT_TID_RINGING_ST) . If an application configured a line to use a ringing cadence, the VP-API would enable the cadence during the Ringing Self Test and cause measurements to be taken during the silent period of the cadence rather than when ringing was applied to the line. The issue would manifest itself as corrupted ringing self test results.
- C2** Prevent large longitudinal capacitive impedances from causing the Line Voltage (LT_TID_LINE_V) test to report false Tip to Ground (vDcTip) or Ring to Ground (vDcRing) voltages.
- C3** Prevent Receiver Off-Hook (LT_TID_ROH) test from incorrectly reporting off-hook phones with a low impedance as a resistive loop (LT_ROHM_RES_LOOP).
- C4** Corrected a Ringer Equivalence Number (REN) test issue in polarity reversal. Starting either electronic ringers test (LT_RINGER_ELECTRONIC_PHNE_TEST or LT_RINGER_ELECTRONIC_PHNE_TEST_3_ELE) in any VP-API-II polarity reversal state (VP_LINE_STANDBY_POLREV, VP_LINE_ACTIVE_POLREV, VP_LINE_OHT_POLREV or VP_LINE_TALK_POLREV) caused the test to report a differential value of 0 REN regardless of the actual impedance on the line.

4.0 ADDITIONS / FEATURES

- C5** Improved accuracy /range of Electronic Ringers Test (LT_RINGER_ELECTRONIC_PHNE_TEST and LT_RINGER_ELECTRONIC_PHNE_TEST_3_ELE) measurements in the presences of large longitudinal capacitive impedances.
- C6** Updated source files to compile without warnings using modern compilers.

5.0 OPERATIONAL NOTES

- N1** **Operational Note:** Customers using VP-API termination type VP_TERM_FXS_GENERIC will observe a reduction in the measurable range of the LT_TID_RD_LOOP_COND imt and ilg results when running from VP-API line states VP_LINE_STANDBY or VP_LINE_STANDBY_POLREV. The ilg and imt return values will be representative of the feed characteristics in these line states causing ilg to report LT_MAX_CURRENT starting at approximately 14mA and imt to report some limited value less than the programed ILA.

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